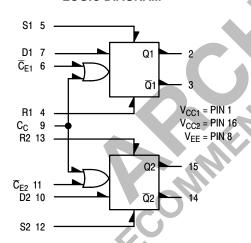
# High Speed Dual Type D Master-Slave Flip-Flop

The MC10231 is a dual master–slave type D flip–flop. Asynchronous Set (S) and Reset (R) override Clock ( $C_C$ ) and  $\overline{Clock}$   $\overline{Enable}$  ( $\overline{C}_E$ ) inputs. Each flip–flop may be clocked separately by holding the common clock in the low state and using the enable inputs for the clocking function. If the common clock is to be used to clock the flip–flop, the  $\overline{Clock}$   $\overline{Enable}$  inputs must be in the low state. In this case, the enable inputs perform the function of controlling the common clock.

The output states of the flip-flop change on the positive transition of the clock. A change in the information present at the data (D) input will not affect the output information at any other time due to master-slave construction.

- $P_D = 270 \text{ mW typ/pkg (No Load)}$
- $t_{pd} = 2 \text{ ns typ}$
- $t_{Tog} = 225 \text{ MHz typ}$
- $t_r$ ,  $t_f = 2.0$  ns typ (20%–80%)

# LOGIC DIAGRAM



# **CLOCKED TRUTH TABLE**

С	D	Q <sub>n+1</sub>
L	Х	$Q_{n}$
Н	L	L
Н	Н	Н

 $C = \overline{C_E} + C_C$ . A clock H is a clock transition from a low to a high state.

### **R-S TRUTH TABLE**

R	s	Q <sub>n+1</sub>
L	L	Qn
L	Н	Н
Н	L	L
Н	Н	N.D.

N.D. = Not Defined



# ON Semiconductor

http://onsemi.com

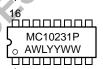
# MARKING DIAGRAMS



CDIP-16 L SUFFIX CASE 620 MC10231L AWLYYWW



PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775

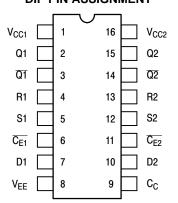


A = Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

# **DIP PIN ASSIGNMENT**



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

### **ORDERING INFORMATION**

Device	Package	Shipping
MC10231L	CDIP-16	25 Units / Rail
MC10231P	PDIP-16	25 Units / Rail
MC10231FN	PLCC-20	46 Units / Rail

# **ELECTRICAL CHARACTERISTICS**

			Test Limits							
		Pin Under	-30	0∘C		+25°C		+85	5°C	
Characteristic	Symbol	Test	Min	Max	Min	Тур	Max	Min	Max	Unit
Power Supply Drain Current	ΙE	8		72		52	65		72	mAdc
Input Current	I <sub>inH</sub>	4 5 6 7 9		650 650 350 350 460			410 410 220 220 290		410 410 220 220 290	μAdc
	I <sub>inL</sub>	4, 5* 6, 7, 9*			0.5 0.5					μAdc
Output Voltage Logic 1	V <sub>OH</sub>	2 2†	-1.060 -1.060	-0.890 -0.890	-0.960 -0.960		-0.810 -0.810	-0.890 -0.890	-0.700 -0.700	Vdc
Output Voltage Logic 0	$V_{OL}$	3 3†	-1.890 -1.890	-1.675 -1.675	-1.850 -1.850		-1.650 -1.650	-1.825 -1.825	-1.615 -1.615	Vdc
Threshold Voltage Logic 1	V <sub>OHA</sub>	2 2†	-1.080 -1.080		-0.980 -0.980			-0.910 -0.910		Vdc
Threshold Voltage Logic 0	V <sub>OLA</sub>	3 3†		-1.655 -1.655			-1.630 -1.630		-1.595 -1.595	Vdc
Switching Times (50 $\Omega$ Load) Clock Input										ns
Propagation Delay	t <sub>9+2-</sub> t <sub>6+2+</sub>	2 2	1.5 1.5	3.4 3.4	1.5 1.5	2.0 2.0	3.3 3.3	1.6 1.6	3.7 3.7	
Rise Time (20 to 80%)	t <sub>2+</sub>	2	0.9	3.3	1.0	1.3	3.1	1.0	3.6	
Fall Time (20 to 80%)	t <sub>2-</sub>	2	0.9	3.3	1.0	1.3	3.1	1.0	3.6	
Set Input Propagation Delay	t <sub>5+2+</sub> t <sub>12+15+</sub> t <sub>5+3</sub> t <sub>12+14</sub>	2 15 3 14	1.1 1.1 1.1	3.4 3.4 3.4 3.4	1,1 1.1 1.1 1.1	2.0 2.0 2.0 2.0 2.0	3.3 3.3 3.3 3.3	1.2 1.2 1.2 1.2	3.7 3.7 3.7 3.7	ns
Reset Input Propagation Delay	t <sub>4+2</sub> - t <sub>13+15</sub> - t <sub>4+3</sub> - t <sub>13+14+</sub>	2 15 3 14	1.1 1.1 1.1 1.1	3.4 3.4 3.4 3.4	1.1 1.1 1.1 1.1	2.0 2.0 2.0 2.0	3.3 3.3 3.3 3.3	1.2 1.2 1.2 1.2	3.7 3.7 3.7 3.7	ns
Setup Time	t <sub>setup</sub>	7	1.5		1.0			1.5		ns
Hold Time	t <sub>hold</sub>	7	0.9		0.75			0.9		ns
Toggle Frequency (Max)	f <sub>tog</sub>	2	200		200	225		200		MHz

<sup>\*</sup> Individually test each input; apply V<sub>ILmin</sub> to pin under test.

 $<sup>\</sup>mathrm{V}_{\mathrm{IHmax}}$  $\dagger$  Output level to be measured after a clock pulse has been applied to the  $\overline{C}_{\text{E}}$  Input (Pin 6)  $V_{\text{ILmin}}$ 

# **ELECTRICAL CHARACTERISTICS** (continued)

			TEST VOLTAGE VALUES (Volts)					
	@ Test Te	mperature	V <sub>IHmax</sub>	V <sub>ILmin</sub>	V <sub>IHAmin</sub>	V <sub>ILAmax</sub>	V <sub>EE</sub>	
		–30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
		+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
		+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
		Pin	TEST V	OLTAGE A	PPLIED TO I	PINS LISTED E	BELOW	, , ,
Characteristic	Symbol	Under Test	V <sub>IHmax</sub>	V <sub>ILmin</sub>	V <sub>IHAmin</sub>	V <sub>ILAmax</sub>	V <sub>EE</sub>	(V <sub>CC</sub> ) Gnd
Power Supply Drain Current	Ι <sub>Ε</sub>	8					8	1, 16
Input Current	l <sub>inH</sub>	4 5 6 7 9	4 5 6 7 9				8 8 8 8	1, 16 1, 16 1, 16 1, 16 1, 16
	I <sub>inL</sub>	4, 5* 6, 7, 9*		*			8	1, 16 1, 16
Output Voltage Logic 1	V <sub>OH</sub>	2 2†	5 7				8 8	1, 16 1, 16
Output Voltage Logic 0	V <sub>OL</sub>	3 3†	5 7			In.	8 8	1, 16 1, 16
Threshold Voltage Logic 1	V <sub>OHA</sub>	2 2†			5 7	9	8 8	1, 16 1, 16
Threshold Voltage Logic 0	V <sub>OLA</sub>	3 3†			5 7	9	8 8	1, 16 1, 16
Switching Times (50Ω Load) Clock Input			+1.11Vdc		Pulse In	Pulse Out	−3.2 V	+2.0 V
Propagation Delay	t <sub>9+2-</sub> t <sub>6+2+</sub>	2 2	7		9 6	2 2	8 8	1, 16 1, 16
Rise Time (20 to 80%)	t <sub>2+</sub>	2	7		9	2	8	1, 16
Fall Time (20 to 80%)	t <sub>2-</sub>	2			9	2	8	1, 16
Set Input Propagation Delay	t <sub>5+2+</sub> t <sub>12+15+</sub> t <sub>5+3-</sub> t <sub>12+14-</sub>	2 15 3 14	6 9		5 12 5 12	2 15 3 14	8 8 8 8	1, 16 1, 16 1, 16 1, 16
Reset Input Propagation Delay	t <sub>4+2</sub> - t <sub>13+15</sub> - t <sub>4+3</sub> - t <sub>13+14+</sub>	2 15 3 14	6		4 13 4 13	2 15 3 14	8 8 8 8	1, 16 1, 16 1, 16 1, 16
Setup Time	t <sub>setup</sub>	7			6, 7	2	8	1, 16
Hold Time	t <sub>hold</sub>	7			6, 7	2	8	1, 16
Toggle Frequency (Max)	f <sub>tog</sub>	2	* *		6	2	8	1, 16

<sup>\*</sup> Individually test each input applying V<sub>IH</sub> or V<sub>IL</sub> to input under test.

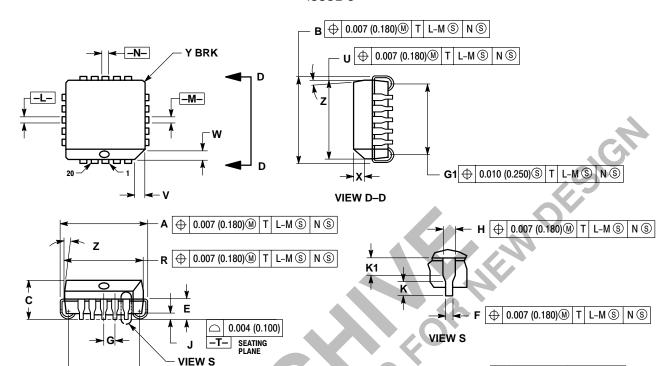
Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibitum has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

 $<sup>\</sup>dagger$  Output level to be measured after a clock pulse has been applied to the  $\overline{C}_E$  Input (Pin 6)  $V_{ILmin}$   $V_{ILmin}$ 

#### PACKAGE DIMENSIONS

### PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



#### NOTES:

G1 ⊕ 0.010 (0.250)③ T L-M ⑤ N ⑤

OF VICE NOT PRESCO

- IOTES:

  1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

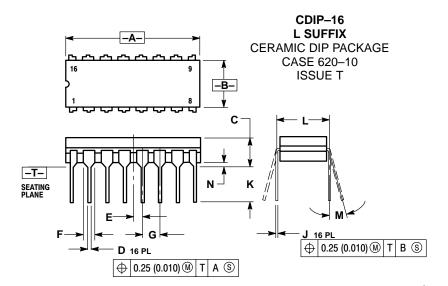
  2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

  3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

  4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Ε	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y		0.020		0.50
Z	2°	10°	2°	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

#### PACKAGE DIMENSIONS



#### NOTES:

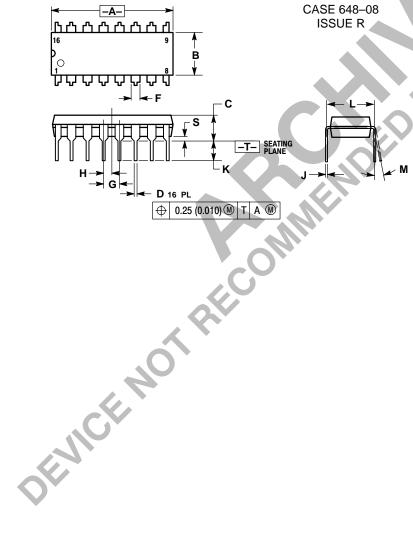
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: INCH.
   DIMENSION LTO CENTER OF LEAD WHEN CONTROLLING DIMENSION LTO CENTER OF LEAD WHEN

- FORMED PARALLEL

  DIMENSION F MAY NARROW TO 0.76 (0.030)
  WHERE THE LEAD ENTERS THE CERAMIC
  BODY.

	INC	HES	MILLIN	IETERS	
DIM	MIN MAX		MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
E	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62 BSC		
M	0 °	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	





- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIN	IETERS		
DIM	MIN MAX		MIN	MAX		
Α	0.740	0.770	18.80	19.55		
В	0.250	0.270	6.35	6.85		
С	0.145	0.175	3.69	4.44		
D	0.015	0.021	0.39	0.53		
F	0.040	0.70	1.02	1.77		
G	0.100	BSC	2.54	54 BSC		
Н	0.050	BSC	1.27 BSC			
J	0.008	0.015	0.21	0.38		
K	0.110	0.130	2.80	3.30		
L	0.295	0.305	7.50	7.74		
M	0°	10°	0°	10 °		
S	0.020	0.040	0.51	1.01		

# **Notes**



# **Notes**





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